AMENDMENT TO THE SPECIFICATION

Please amend the specification paragraphs set forth below to read as follows:

Two paragraphs at page 7, lines 10-25:

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FIGURE 1 is a cross-section schematic diagram of a two-layer carrier structure comprising a carrier liner 10 and a cross-linkable adhesive layer 20. Carrier structures of the present invention may also include cross-linkable adhesive layers 20 comprising a combination of permanent tacky controlled peel strength adhesive and thermal-UV releasing adhesive within a single layer 20. Thus, differential peel strength is produced after thermal-UV exposure. The adhesive layer 20 first releases the chips or other objects carried and then releases the carrier base 10, enabling the replacement of adhesive layer 20 for reuse of typical carrier base 10. Such a combination adhesive preferably releases both chips 60 and liner 10 without leaving a residue, and also preferably has greater adhesion to liner 10 than to the chip or other object 60 carried so that the chip is released more easily than is the liner 10.

With the use of thermal-UV releasing tacky layer 20, the adhesion is very strong during the transporting and handling, as long as the cross-linkable layer 20 is protected from exposure to thermal-UV energy. The release of the chips 60 is made dramatically easier by exposure of the tacky layer 20 to thermal-UV, generally right before the pick-and-place operation or other use or process.

Paragraph at page 9, lines 21-26:

It is noted that the tackiness adjustment desirably is made with the size, weight, and nature of the object 60 to be carried in mind. Where the object 60 has a relatively large smooth area that contacts the tacky adhesive, as is the case for a large area semiconductor chip, a lesser tackiness is sufficient. For an object 60 that has a contact area that is only a relatively small portion of its size, as is the case for a finned surface of a heat sink device, somewhat greater adhesion may be desired.